

Heatsinks f.cool

- ▶ Profile heatsinks and fluid coolers
- ▶ Heatsinks and active heatsinks for processors
- ▶ Board Level heatsinks
- ▶ Cooling aggregates
- ▼ Accessories for electronic components
 - ▼ Thermal conductive material
 - Silicone rubber insulating material for semiconductors
 - Thermally conductive foil made of siliconelastomer
 - Silicone-free thermal conductive foils
 - High thermoconducting graphite foils
 - Thermally conductive foil both sides adhesive
 - [Heat conductive foam and gel foils](#)
 - Kapton insulator washers
 - Mica wafers
 - Aluminium oxide wafers
 - Thermal conductive paste and thermal interface film
 - Thermally conductive adhesive
 - ▶ Fixing material for mechanical components
 - ▶ Mounting material for single semiconductors and heatsinks

Cases f.case

Connectors f.con

Heat conductive foam and gel foils

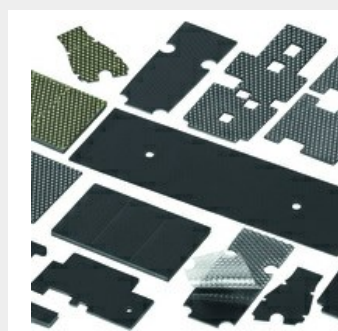
GEL ...

GEL 30

highly heat-conductive silocon foil
smooth, elastic and compressible
equals uneven surfaces very well (Gap-Filler)

Data sheet

add to request



Features Variants Service Accessories / related products

material	GEL foil
material thickness	3 mm
tolerance	0.3
thermal resistance R_{th} (100 kPa)	15.15 °C cm ² /W
thermal resistance (100 kPa) R_{th} (100 kPa)	2.35 °C in ² /W
version	standard
colour	dark gray
thermal conductivity	1.5 W/m·K
hardness	49 Shore 00
density	2.6 g/cm ³
temperature range	-60°C ... +200°C
elongation	100 %
volume resistance	1·10 ⁶ MΩ/m
dielectric constant	5.8 [50 Hz] 5.6 [1 KHz] 5.5 [1 MHz]
dielectric loss factor	0.048 [50 Hz] 0.015 [1 KHz] 0.003 [1 MHz]
dielectric strength	14 kV/mm (AC)
class of inflammability	UL 94 V-0
type of delivery	cuttings on customer's requirements plates, usable area 300x200mm on both sides covered with protective foil